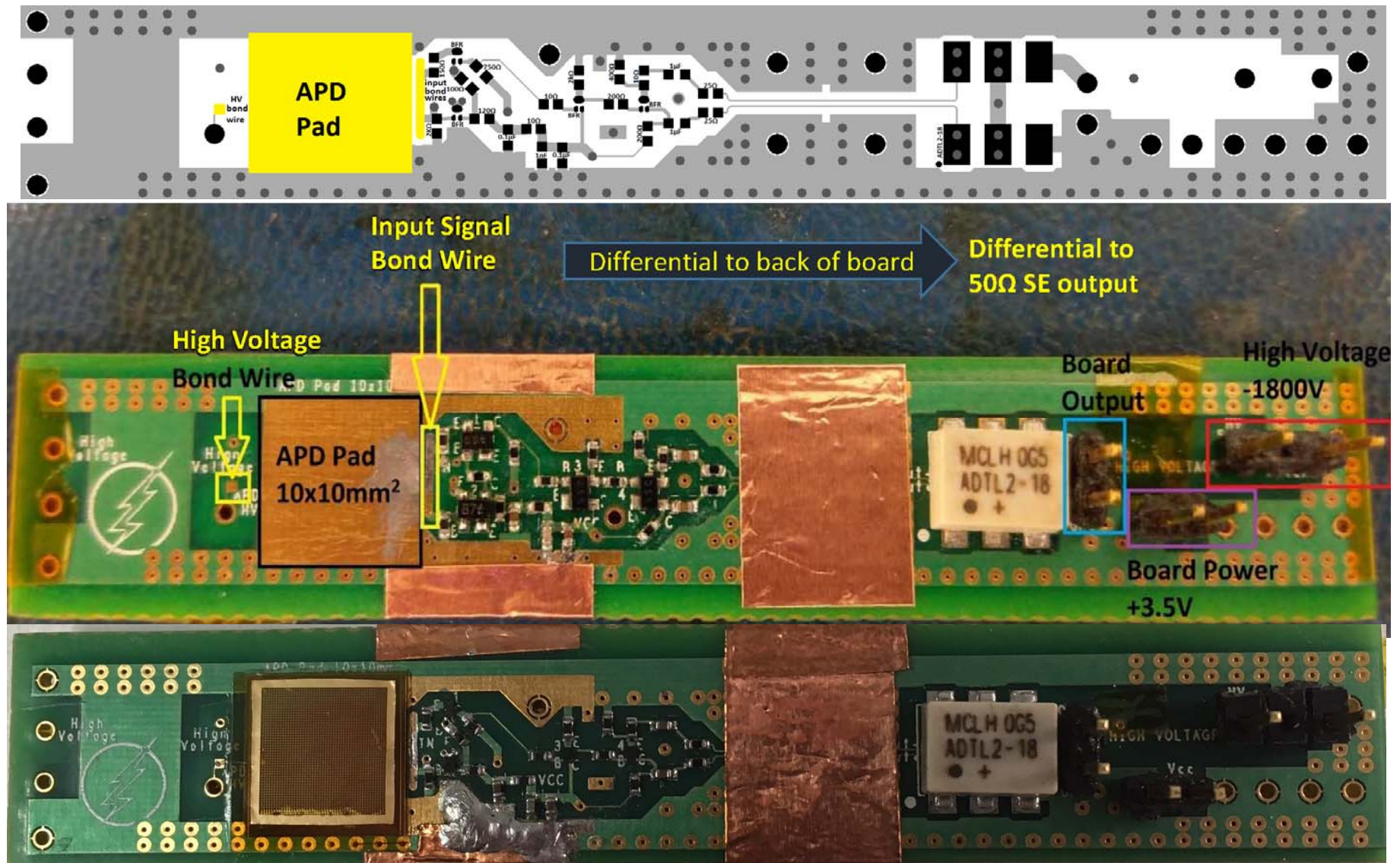


# Packaging of RMD APDs with External Mesh Electrodes on U-Penn Amplifiers

# Bert Harrop

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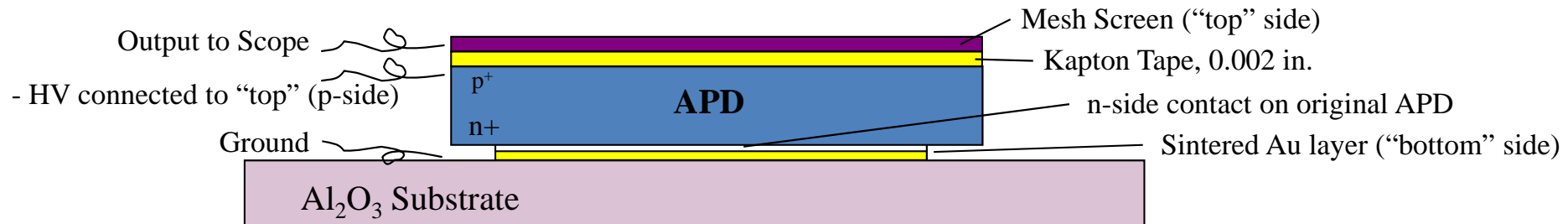
Mar. 17, 2017





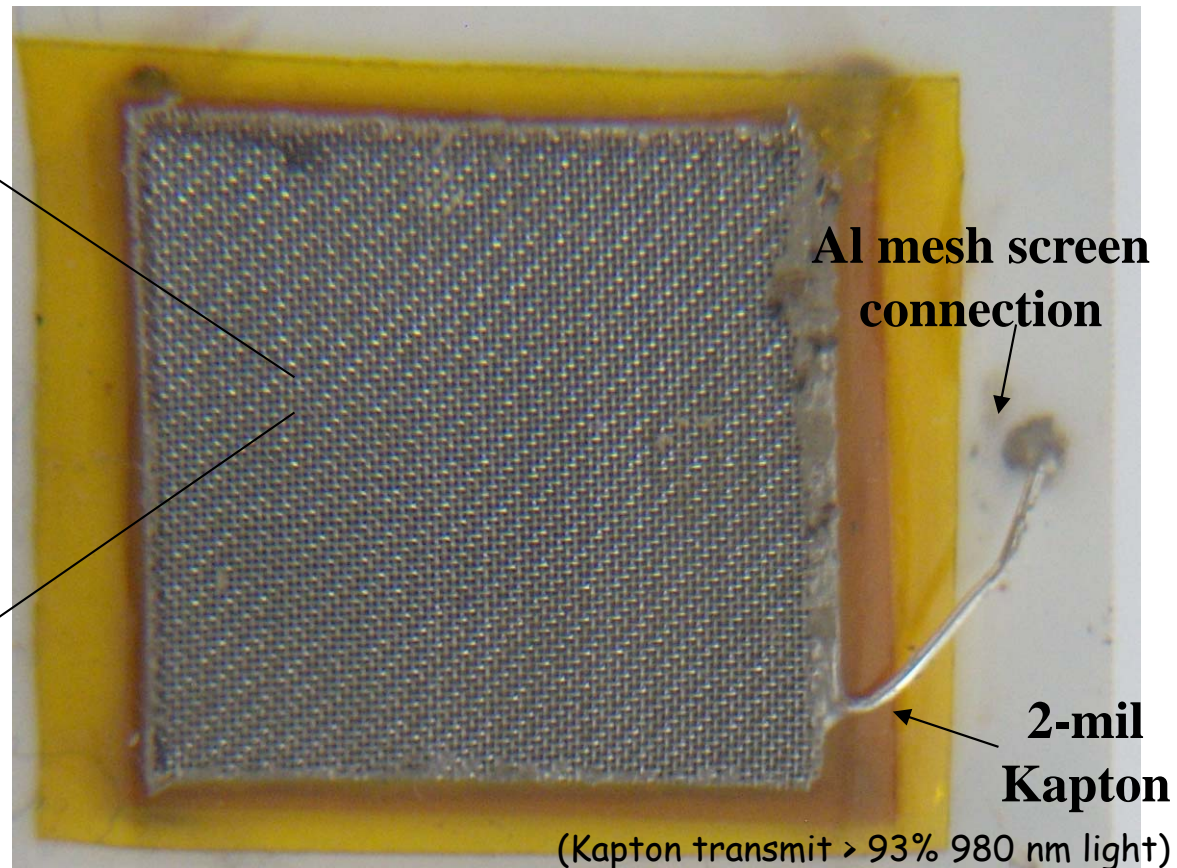
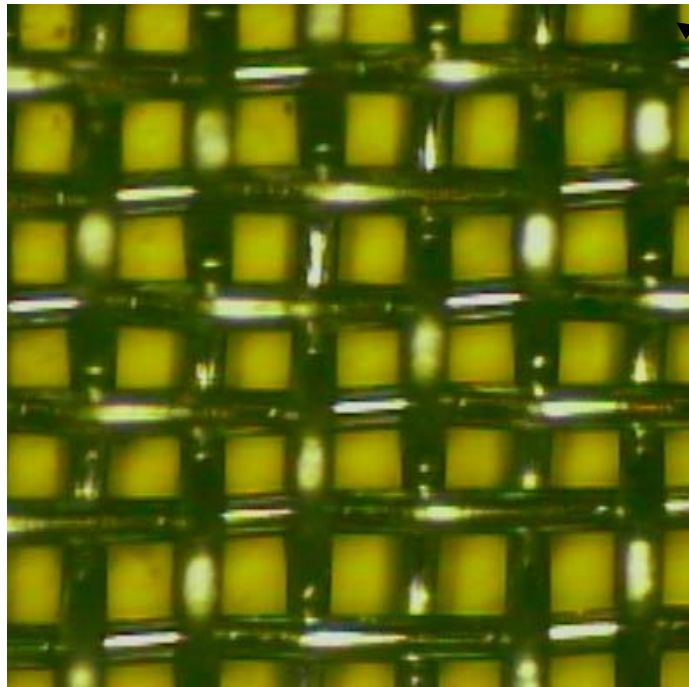
# RMD 8x8 mm<sup>2</sup> APD - Al-mesh-screen scenario (Nov. 15, 2012)

[http://physics.princeton.edu/~mcdonald/LHC/Tsang/APD\\_8x8mm\\_mesh\\_screen\\_111512k.ppt](http://physics.princeton.edu/~mcdonald/LHC/Tsang/APD_8x8mm_mesh_screen_111512k.ppt)  
Sketch by Thomas Tsang



Contact between screen and n+ side made by Au epoxy thru hole in Kapton

McMaster 9227T417, 200 mesh, 33.6% open



# 2017: Magnetron Sputtering of Top/Bottom APD Contacts



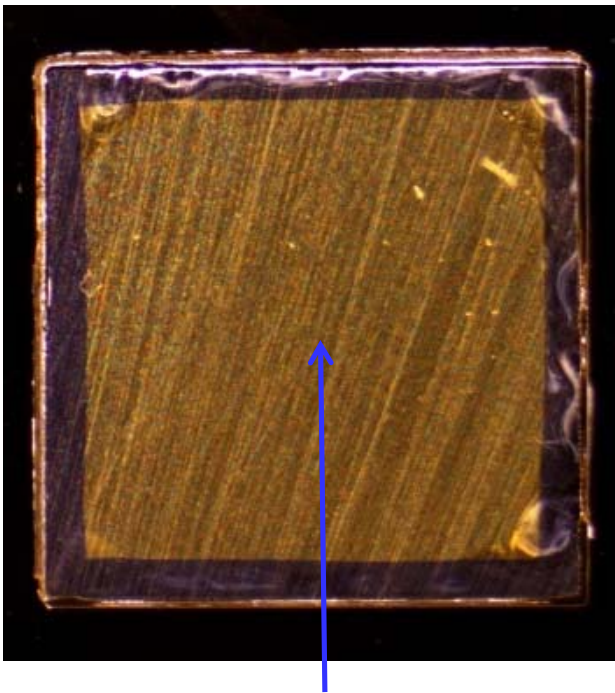
A bare RMD APD die is 10x10 mm<sup>2</sup>.

The sensitive area is about 8x8 mm<sup>2</sup>.

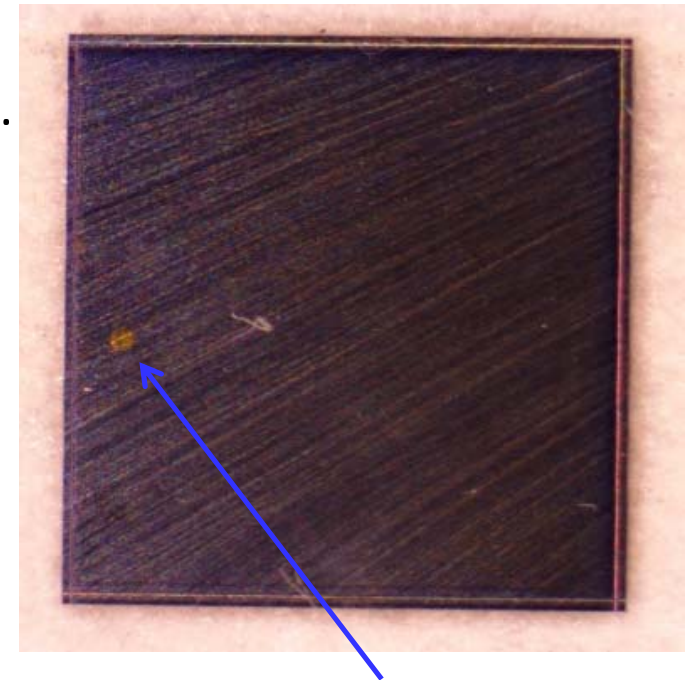
The top (p-side) is photosensitive.  
A small electrical contact is made to the top side.

The bottom (n-side) has a 7x7 mm<sup>2</sup> “mesa,” which serves as a large electrical contact.

These contacts are made by sputtering Ti/Au layers of 20/200 nm.



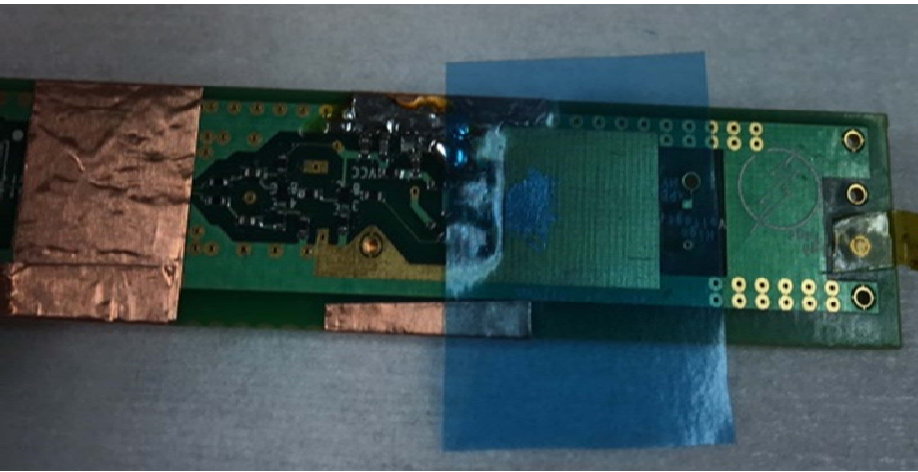
Bottom Contact (Mesa)



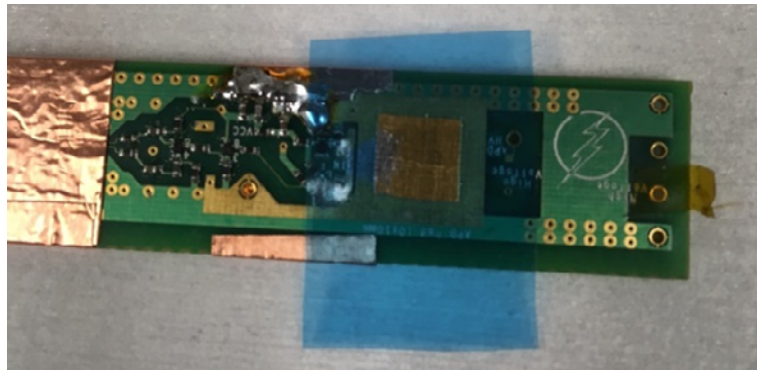
Top Contact (Dot)



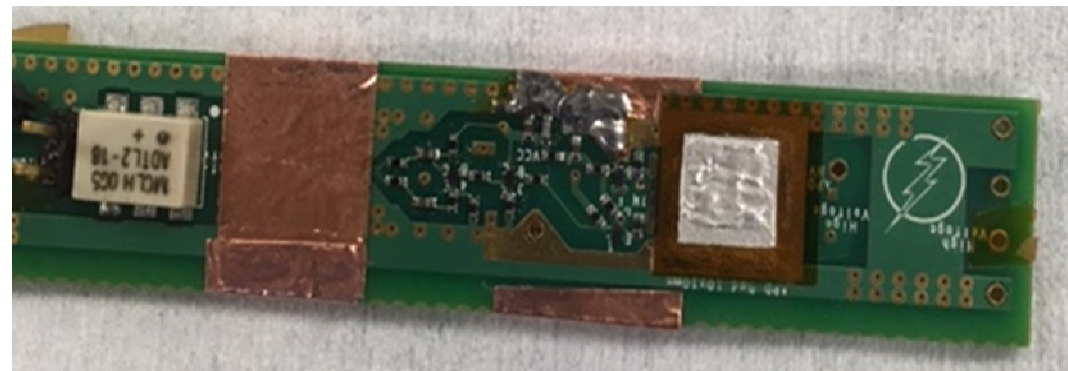
# Applying the conductive H22E Epotek Silver Epoxy to the 10x10 mm<sup>2</sup> Contact Pad of the Penn PCB



Apply Thin Film (50  $\mu$ m) Adhesive

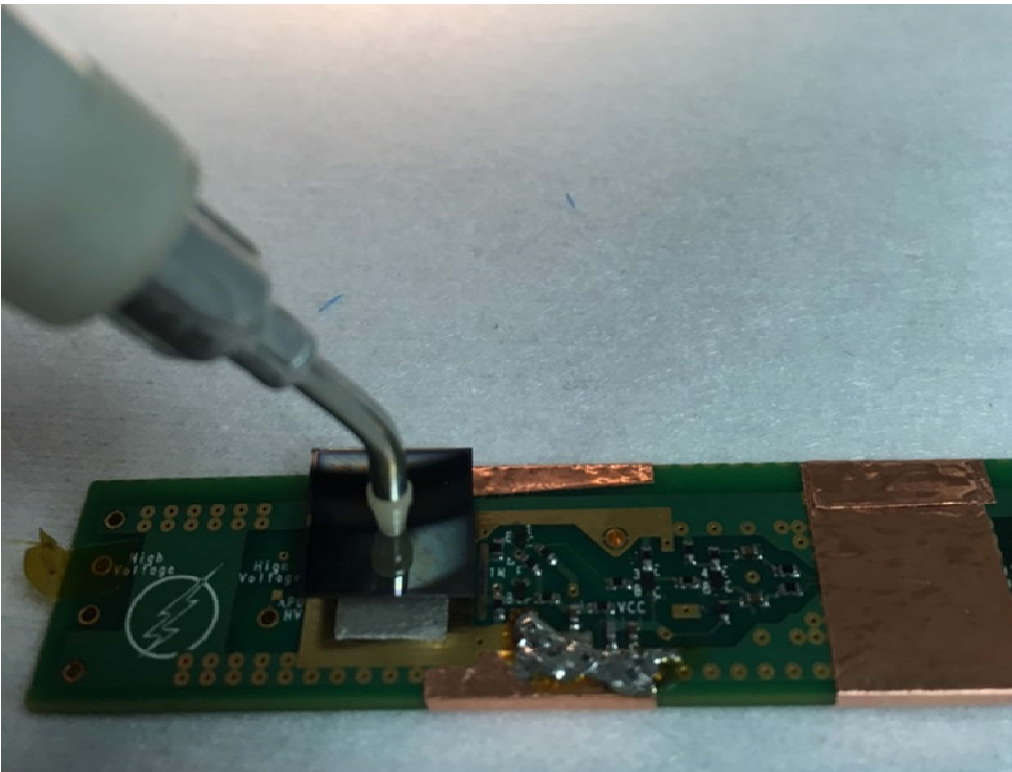


Create 7x7 mm<sup>2</sup> opening in Mask



Apply Silver Epoxy, Remove Mask

# Die Bonding of the APD

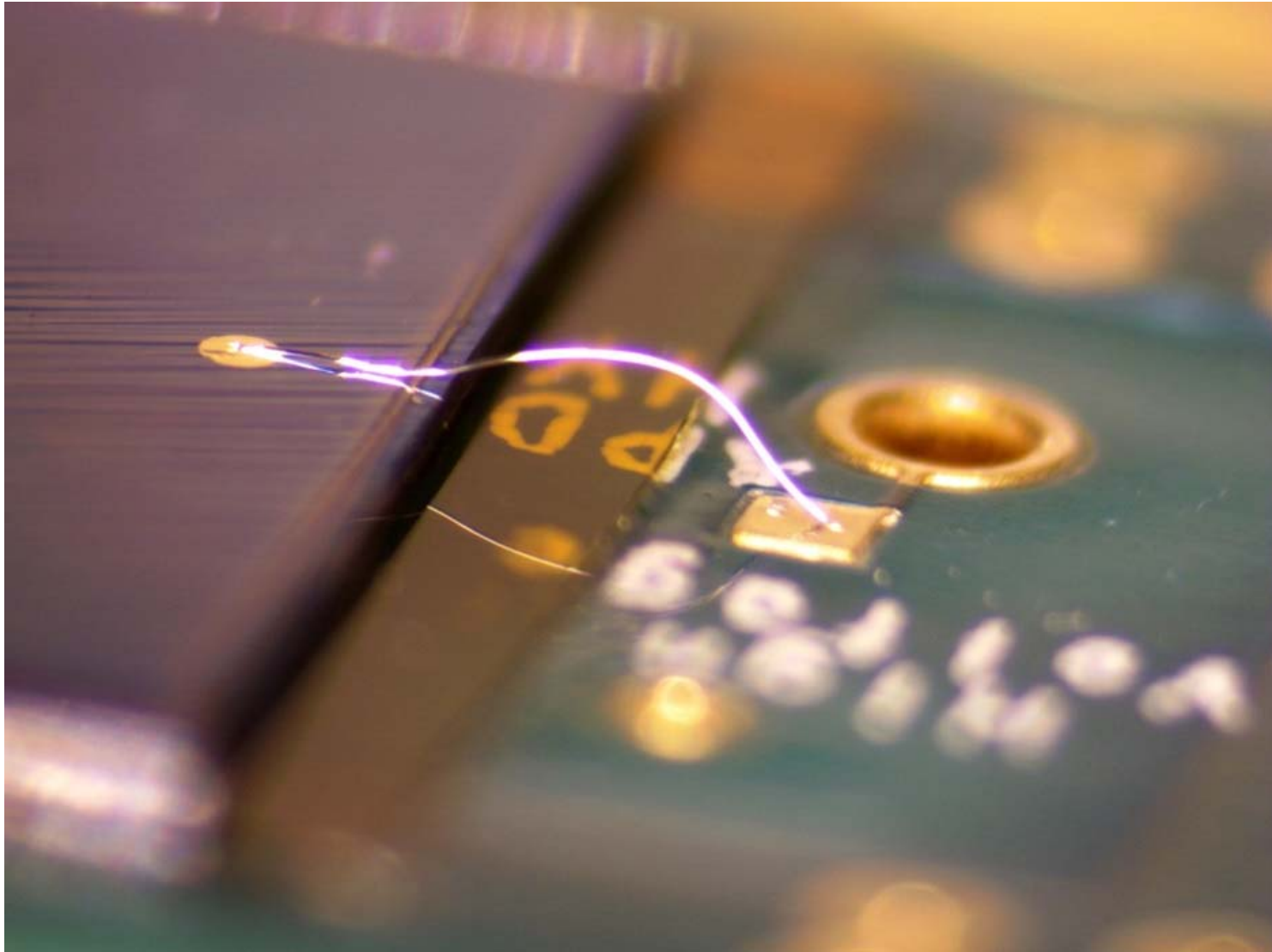


Placing APD onto epoxy



Cure Epoxy in Vacuum Oven  
5 Minutes @ 150C

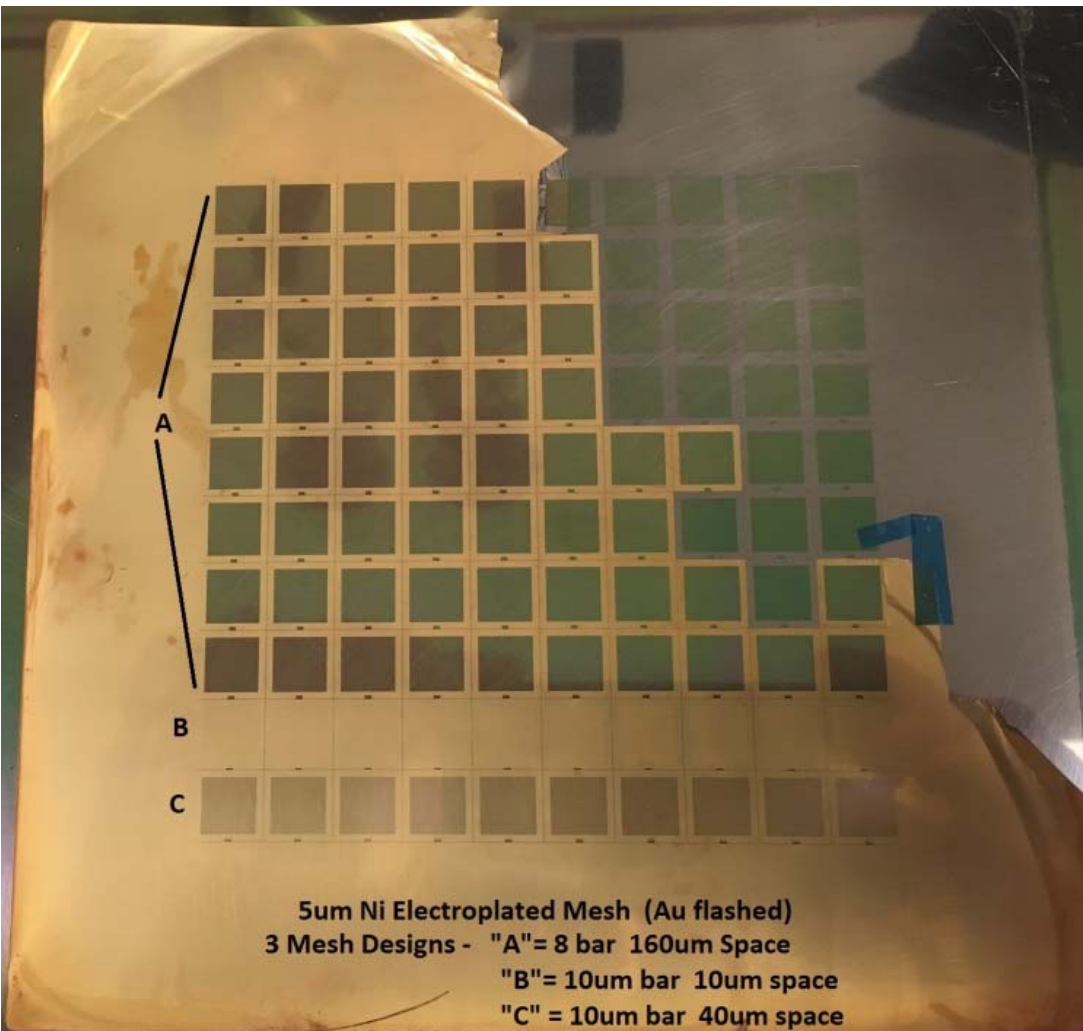
## Wire Bond Top Contact (for –HV)



25- $\mu\text{m}$ -Al Wirebond (Wedge)



# Electroplated Ni Mesh



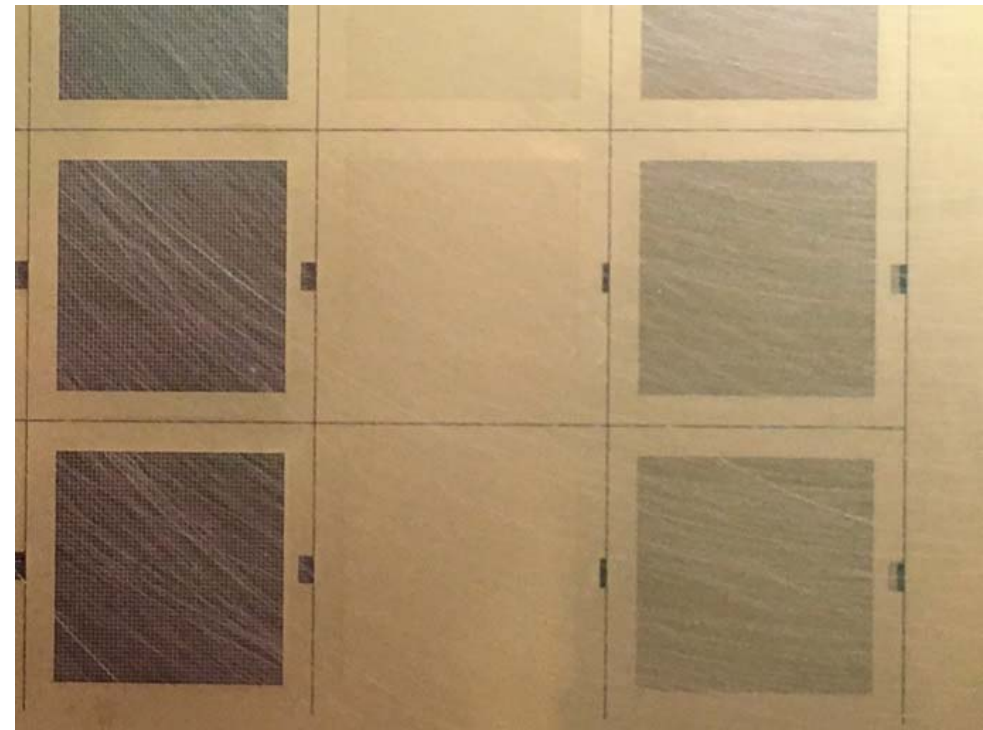
5-μm sheet of 100 electroplated Ni meshes (Au flashed).

3 Mesh Designs:

A = 8-μm bar, 160-μm spacing, 90% open

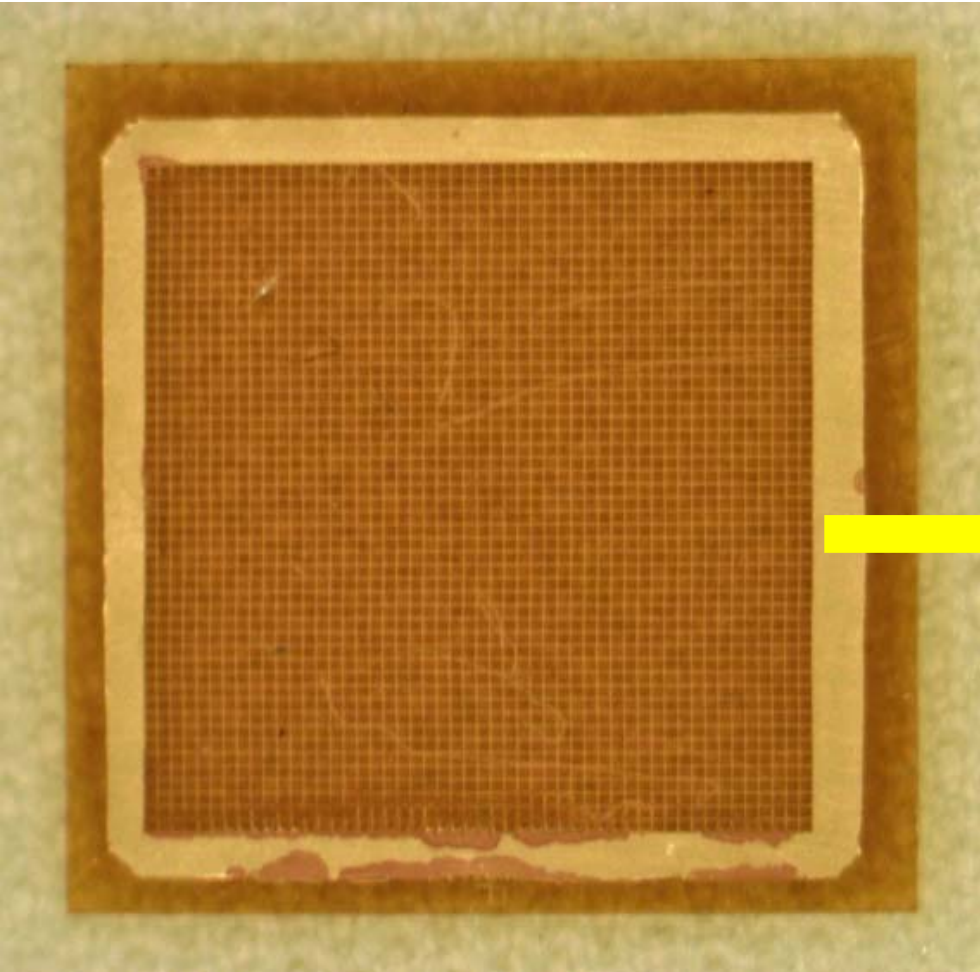
B = 10-μm bar, 10-μm spacing, 11% open

C = 10-μm bar, 40-μm spacing, 64% open

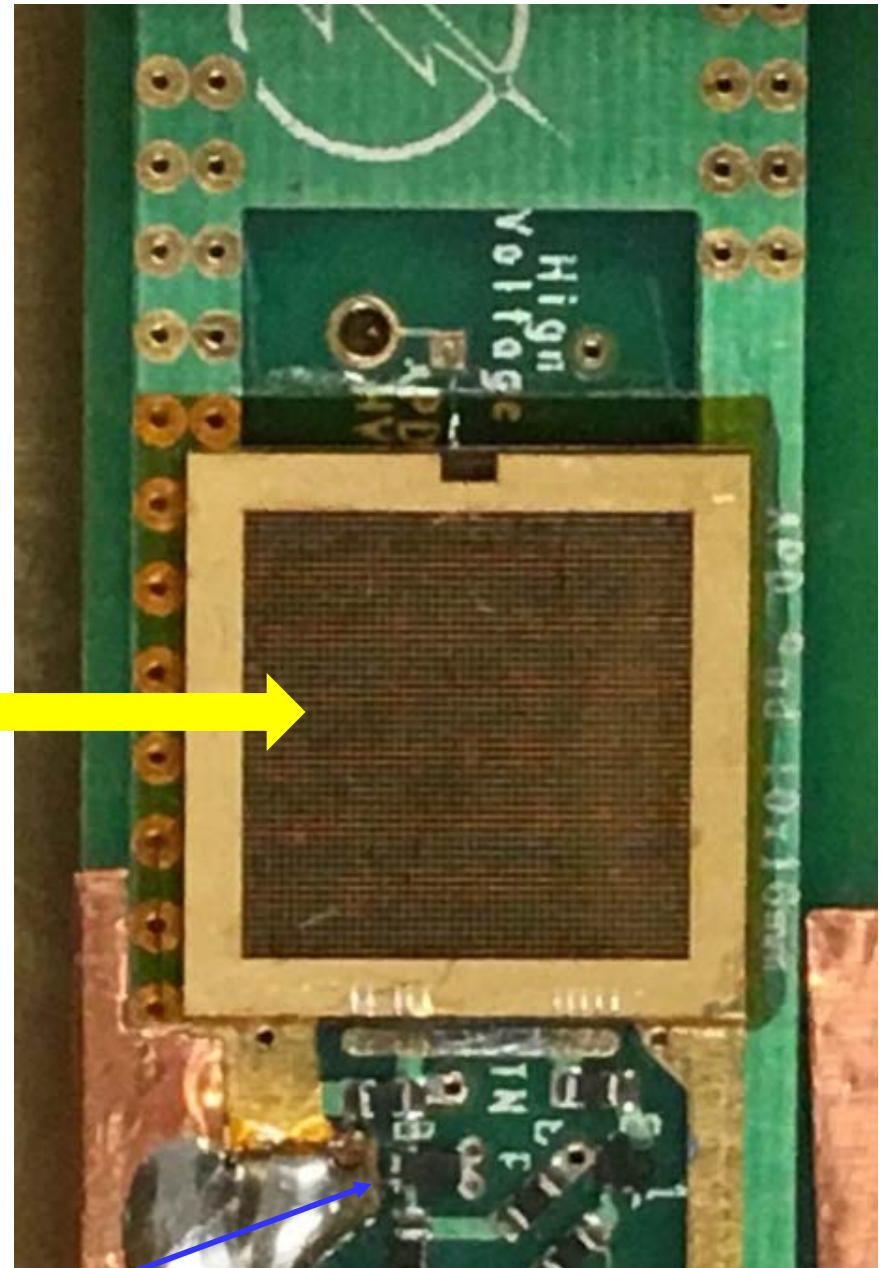


We use the type A meshes now.

## Mount Mesh on the APD



Type A Mesh mounted on 50- $\mu\text{m}$  Kapton  
(100-nm-Au flashed)

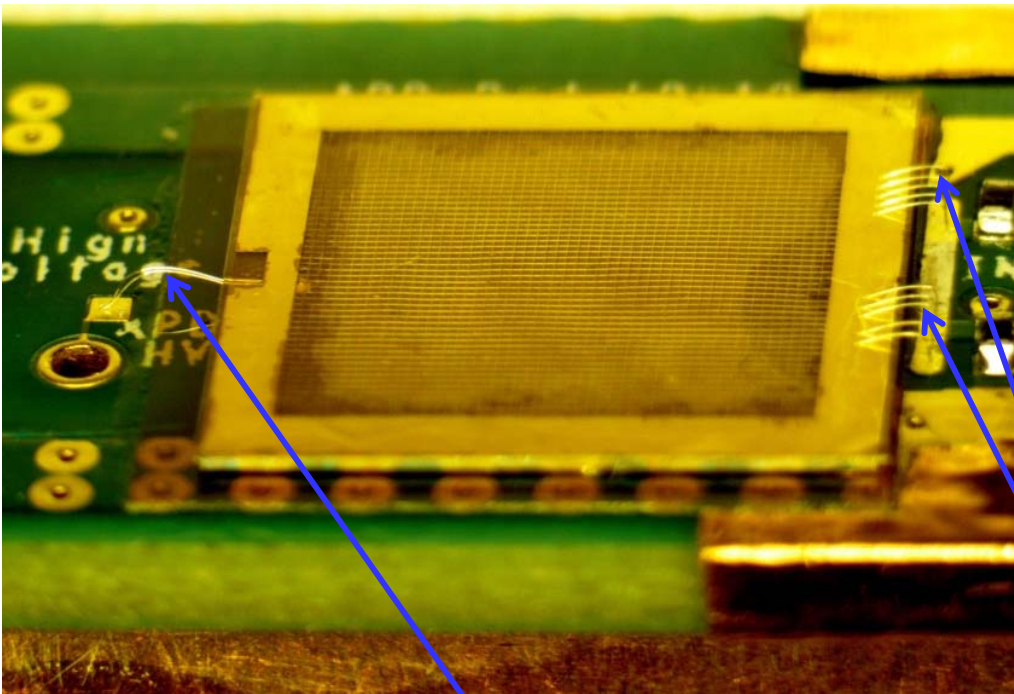


Mesh mounted on APD

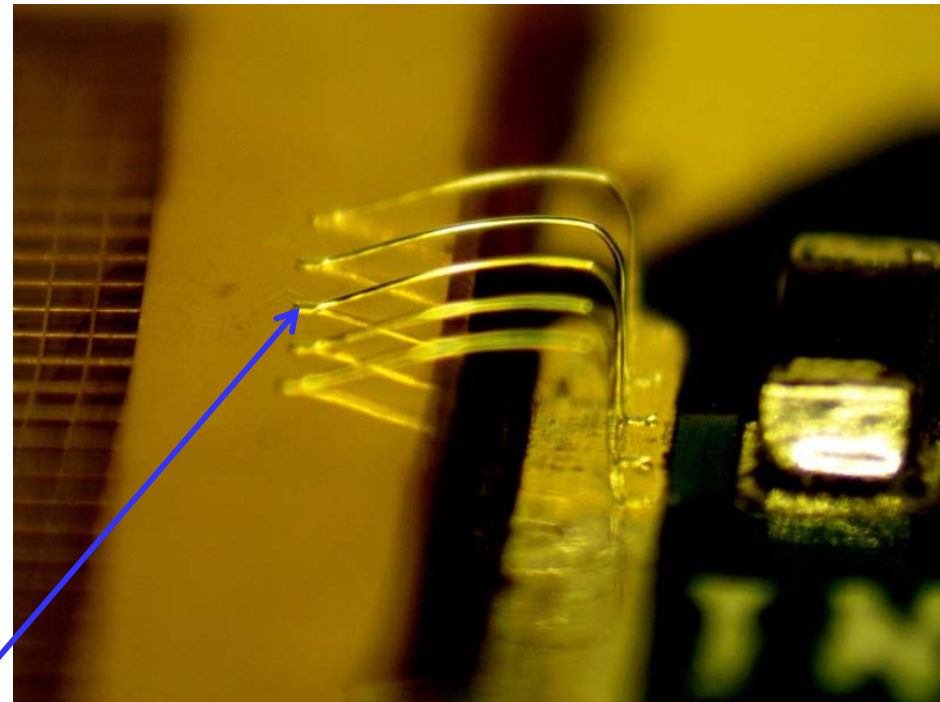
First transistor of the preamp



## Wirebond Mesh to Amplifier Input



-HV Wirebond to top (p-side) contact



Mesh Signal Wirebonds

This version of the preamp/APD operates with the bottom side of the APD at ground, its top side at  $-HV$ , and the mesh at ground.

# Completed APD / Amplifier

